XL-DZ304UYD/1

技术数据表

F3MM

特点（ ）：

* :7.5*6.5*4.5mm

Appearance dimension : 7.5*6.5*4.5mm

* : /

Luminous color and colloid: Yellow Light /Yellow colloid

* ROHS

Environmental protection products meet ROHS requirements

* MSL :2

M

电性参数

Parameter	Symbol	Value	Unit
Max Power Dissipation	PD	50	mW
Max Continuous Forward Current	IF	20	mA
Peak Forward Current	IFP	80	mA
Max Reverse Voltage	VR	5	V
Antistatic ability	ESD	2000	V
Operating Temperature Range	TOPR	-40 ~ +85	
Storage Temperature Range	TSTR	-40 ~ +85	
/ Lead Soldering Temperature/Time	TSOL	260 Ò6S	/S

Luminous Intensity	Iv	300	/	900	mcd	IF=20mA
Dominant Wave Length	λd	585	/	595	nm	IF=20mA
Peak Wave Length	λp	/	590	/	nm	IF=20mA
Forward Voltage	VF	1.8	/	2.4	V	IF=20mA
Half wave width	φ	/	20	/	nm	IF=20mA
Viewing Angle	2Ø1/2	/	45 °	/	deg	IF=20mA
Reverse Current	IR	/	/	≤1	μA	VR=5V

亮度分档

：

代码	最小值	最大值	单位	测试条件
A4	300	400	mcd	IF=20mA
A5	400	500		
A6	500	700		
A7	700	900		

亮度误差±10%　Brightness error ± 10%

电压分档

：

代码	最小值	最大值	单位	测试条件
N12-7	1.8	2.0	V	IF=20mA
N12-8	2.0	2.2		
N12-9	2.2	2.4		

电压误差±0.1V　Voltage error ± 0.1V

波长分档

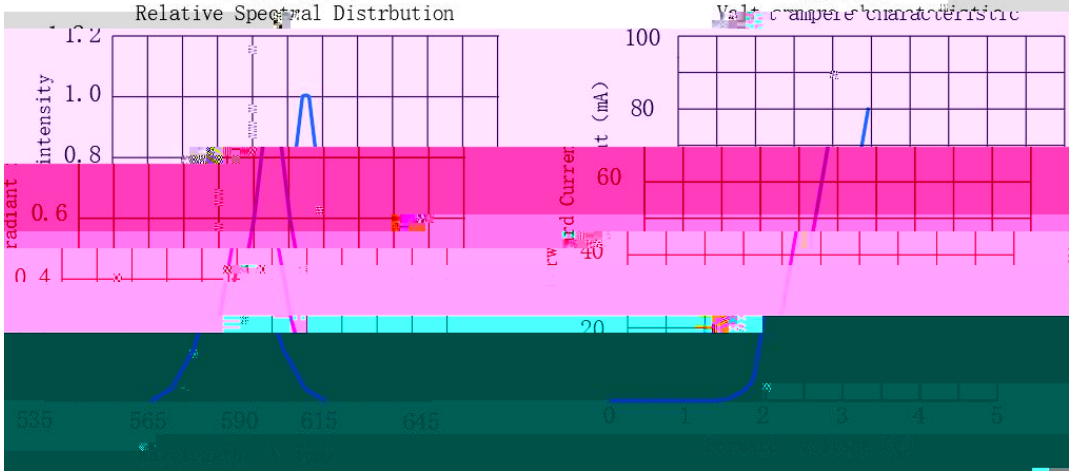
：

代码	最小值	最大值	单位	测试条件
HY04	585	590	nm	IF=20mA
HY05	590	595		

波长误差±1nm　Wavelength error ± 1nm

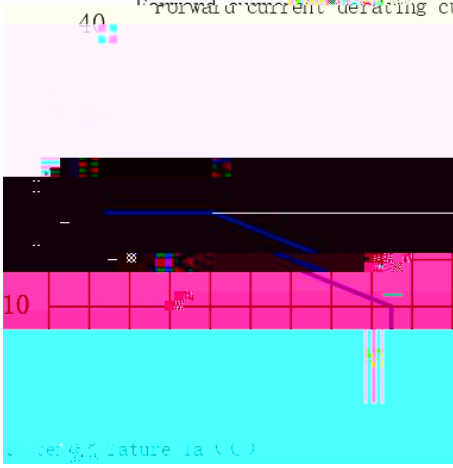
典型特性曲线

光谱分布曲线
Relative Spectral Distrbution

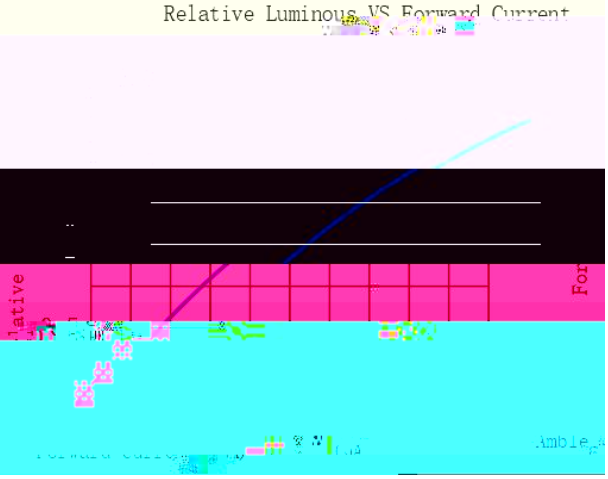


伏安特性

正向电流降额曲线



相对光强与正向电流特性
Relative Luminous VS Forward Current



: 25 + 5 C./Note: If not otherwise indicated, the test environment temperature is 25 + 5 C.

可靠性试验

Reliability Test Items And Conditions

Class	Test item	

包装

注意事項（1）

1、贮存：

* LED !„ypÒ•'R4B•30@Y!@1ad7#@ Ÿ• € 70% LED

Storage environment of LED with temperature not exceeding 30 and relative humidity not exceeding 70%.It is recommended that LDE be used in the original box for no more than three months. If longer storage time is required, put it in the drying box and add desiccant or filled with nitrogen.

2、静电：

*

Part

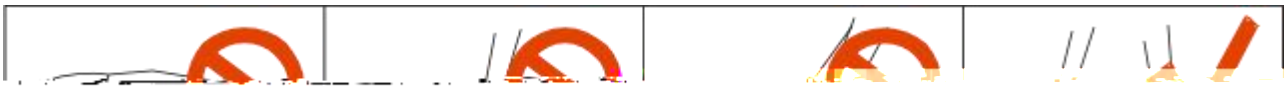
使用注意事项（3）

Precautions (3)

4、其他事项：

*

*When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



*LED

*The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.

5、眼睛保护忠告：